

RB521S

List

List..... 1

Package outline..... 2

Features..... 2

Mechanical data..... 2

Maximum ratings 2

Rating and characteristic curves..... 3

Pinning information.....4

Marking..... 4

Suggested solder pad layout..... 4

Packing information..... 5

Reel packing..... 6

Suggested thermal profiles for soldering processes..... 6

High reliability test capabilities.....7



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RB521S

200mA Surface Mount Small Signal Type-30V

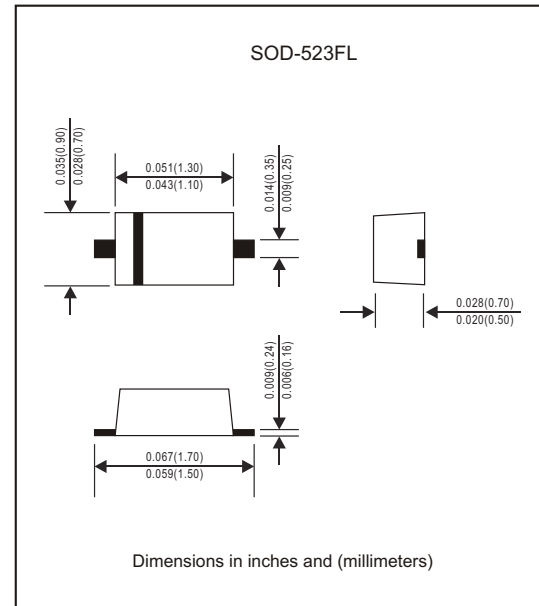
Features

- Low current rectification and high speed switching.
- Extremely small surface mount type.
- Up to 200mA current capability.
- Low forward voltage drop ($V_F = 0.5V$ typ. @200mA)
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet/exceeds environmental standards of MIL-STD-19500/228

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-523FL
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.002gram

Package outline



Maximum ratings (AT $T_A = 25^\circ C$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Repetitive peak reverse voltage		V_{RM}			30	V
Continuous reverse voltage		V_R			30	V
Mean rectifying current		I_O			200	mA
Forward surge current	8.3ms single halfsine-wave superimposed on rate load (JEDEC methode)	I_{FSM}			1000	mA
Capacitance between terminals	f=1MHz and applied 10V DC reverse voltage	C_T		4		pF
Storage temperature		T_{STG}	-65		+175	$^\circ C$
Operating temperature		T_J	-55		+125	$^\circ C$
Forward voltage	$I_F = 200$ mADC	V_F			0.50	V
Reverse current	$V_R = 10$ V DC	I_R			30	μA

Rating and characteristic curves (RB521S)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

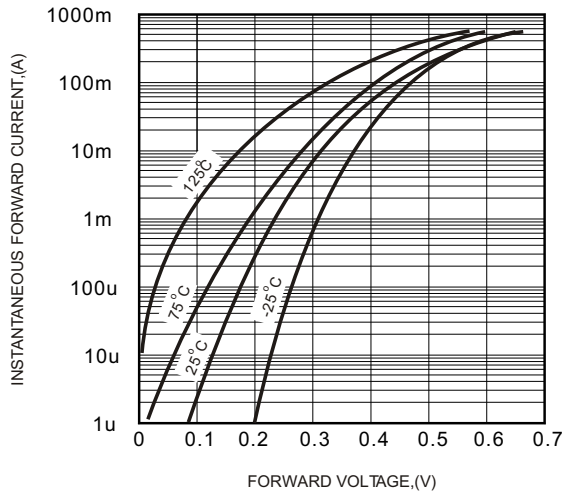


FIG.2 - TYPICAL REVERSE CHARACTERISTICS

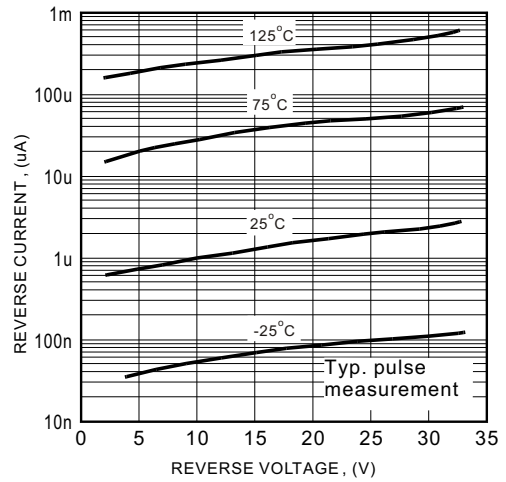
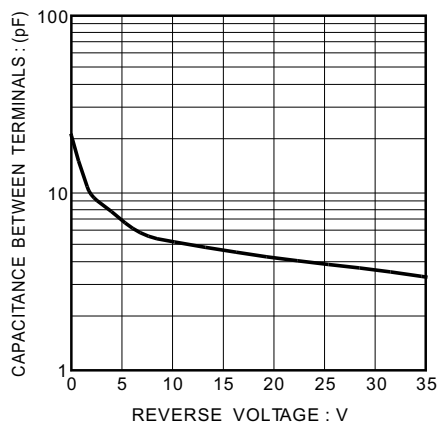




FIG.3-TYPICAL TERMINALS CAPACITANCE



RB521S

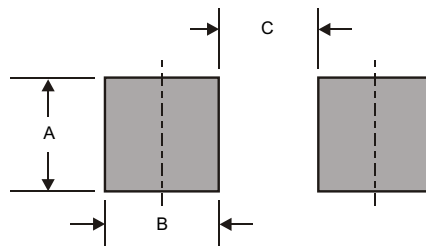
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
RB521S	C, 5M

Suggested solder pad layout

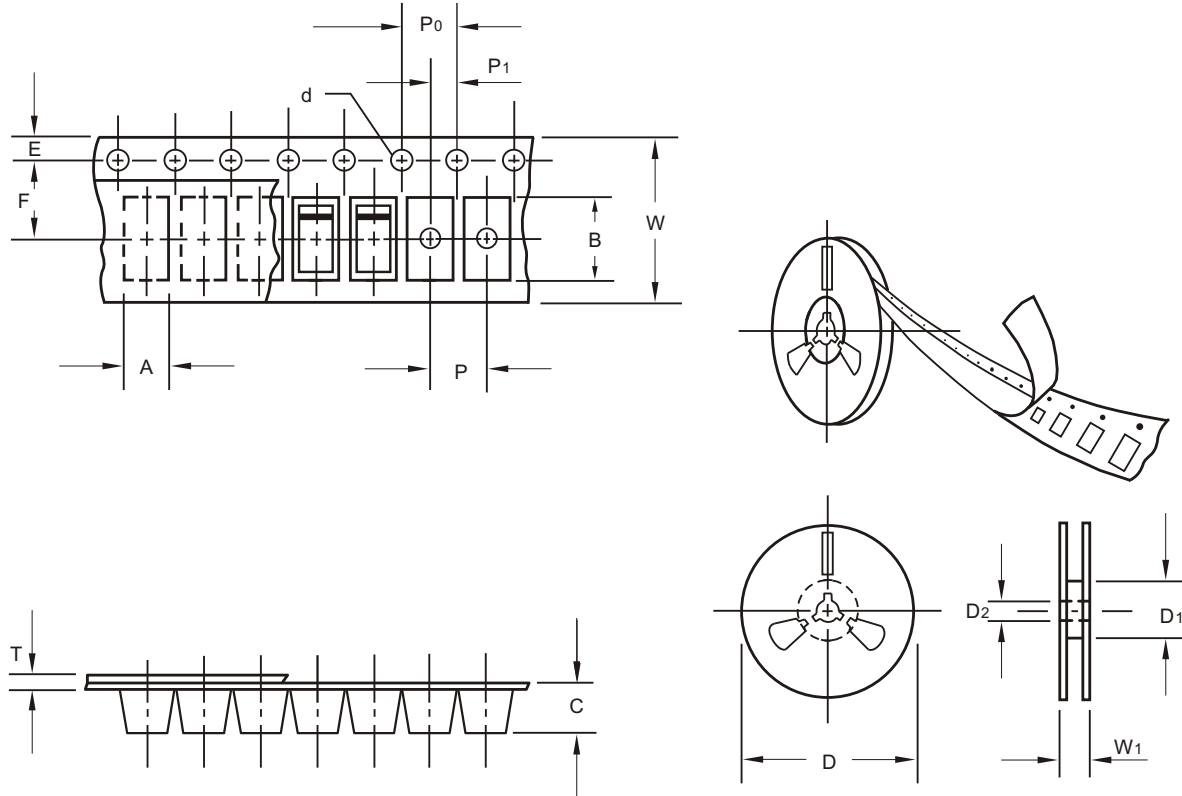


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-523FL	0.016 (0.40)	0.016 (0.40)	0.056 (1.40)

RB521S

Packing information



unit:mm

Item	Symbol	Tolerance	SOD-523FL
Carrier width	A	0.1	0.90
Carrier length	B	0.1	1.40
Carrier depth	C	0.1	0.76
Sprocket hole	d	0.1	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	50.00
Feed hole diameter	D2	0.5	8.40~9.90
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.6
Tape width	W	0.3	8.00
Reel width	W1	1.0	10.90

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

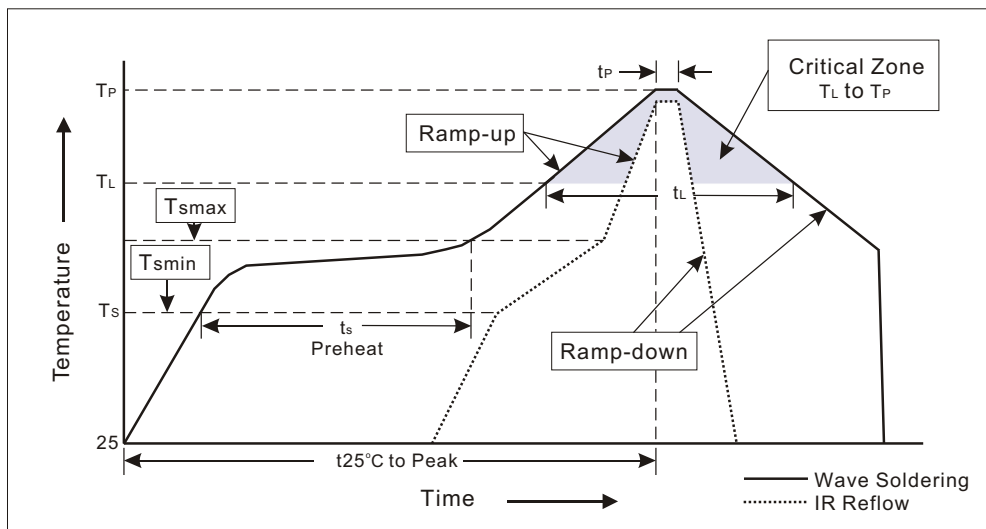
RB521S

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-523FL	7"	3000	4.0	30,000	195*190*140	178	360*355*227	120,000	4.3
							400*300*410	240,000	7.8
							450*395*420	360,000	11.6

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=10°C~35°C Humidity=65%±15%
- 2.Reflow soldering of surface-mount devices



3.Flow (wave)soldering (solder dipping)

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(min to max)(t_s)	100°C 150°C 60~120sec
T_{smax} to T_L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	183°C 60~150sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_p)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

RB521S**High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec. immerse body into solder 1/16"±1/32"	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_A=125^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1026
4. Forward Operation Life	Rated average rectifier current at $T=25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A=121^\circ\text{C}$ for 4 hrs.	
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Thermal Shock	0°C for 5 min. rise to 100°C for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1056
9. Forward Surge	8.3ms single half sine-wave superimposed on rated load, one surge.	MIL-STD-750D METHOD-4066-2
10. Humidity	at $T_A=65^\circ\text{C}$, RH=98% for 1000hrs.	MIL-STD-750D METHOD-1038
11. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031
12. Solvent Resistance	Dip into Freon at 25°C for 1 min.	MIL-STD-202F METHOD-215